**ORDER DESCRIPTION**

1. **Object of the contract**

The subject of the contract is a thermoelectric cooler in the amount of

* thermoelectric cooler 1TE on TO3908 header - 1MD03-002-04 20 pcs
* thermoelectric cooler 1TE on TO3908 header - 1MD03-002-05 20 pcs
* thermoelectric cooler 1TE on TO3908 header - 1MD03-004-04 20 pcs
* thermoelectric cooler 1TE on TO3908 header - 1MD03-005-04 20 pcs
1. **The scope of the subject of the contract**

A detailed description of the subject of the contract is provided in section 5 of this document.

1. **Criterion**

Offers will be evaluated according to a point scale with a maximum number of points of 100.

|  |  |  |
| --- | --- | --- |
| Criterion | Maximum number of points S | Method of awarding points |
| Net Price (P) | 100 | S x Pmin/Pi |

Where:

* Pi – net price of goods - for the given offer
* Pmin - the minimum delivery net price for the ordered goods from all offers submitted
* S – number of points

The final score will be calculated by adding up the partial components and then rounded to two decimal places (rounded from "5" up).

1. **Deadline for completing the order**

**As soon as possible, no later than 8 weeks from the date of placing the order.** **The ordering party requires the application of the FCA Incoterms 2020 delivery principle. FCA (free carrier), i.e. the moment of delivery of the goods is considered to be at the disposal of the courier or other designated person through buyer in the area indicated by the supplier.**

1. **Parameters**

**5.1 Detailed scope of the subject**

|  |  |  |
| --- | --- | --- |
| Product name | Parametrer | Specification |
| thermoelectric cooler 1TE on TO3908 header 1MD03-002-04  |  | Top Ceramics (cold side) | Blank, no metallization |
| Bottom ceramics | Blank, no metallization |
| pellets | BiTe with Ni barrier layer |
| Assembling Solder | Sn-Sb lead free RoHs Tmelt = 230°C |
| TEC bonding | 2x Au wire per pin |
| Header | TO3908.01 |
| Height  | 0,95 mm |
| ΔTmax K  | 73  |
| Qmax W | 0,2 |
| Imax AUmax VACR Ohm  | 1,10,30,18 |
| thermoelectric cooler 1TE on TO3908 header 1MD03-002-05  |  | Top Ceramics (cold side) | Blank, no metallization |
| Bottom ceramics | Blank, no metallization |
| pellets | BiTe with Ni barrier layer |
| Assembling Solder | Sn-Sb lead free RoHs Tmelt = 230°C |
| TEC bonding | 2x Au wire per pin |
| Header | TO3908.01 |
| Height  | 1.05 mm |
| ΔTmax K  | 73  |
| Qmax W | 0,1 |
| Imax AUmax VACR Ohm  | 0,90,30,22 |
| thermoelectric cooler 1TE on TO3908 header 1MD03-004-04  |  | Top Ceramics (cold side) | Blank, no metallization |
| Bottom ceramics | Blank, no metallization |
| pellets | BiTe with Ni barrier layer |
| Assembling Solder | Sn-Sb lead free RoHs Tmelt = 230°C |
| TEC bonding | 2x Au wire per pin |
| Header | TO3908.01 |
| Height  | 0,95 mm |
| ΔTmax K  | 73  |
| Qmax W | 0,4 |
| Imax AUmax VACR Ohm  | 1,10,50,35 |
| thermoelectric cooler 1TE on TO3908 header 1MD03-005-04 |  | Top Ceramics (cold side) | Blank, no metallization |
| Bottom ceramics | Blank, no metallization |
| pellets | BiTe with Ni barrier layer |
| Assembling Solder | Sn-Sb lead free RoHs Tmelt = 230°C |
| TEC bonding | 2x Au wire per pin |
| Header | TO3908.01 |
| Height  | 0,95 mm |
| ΔTmax K  | 73  |
| Qmax W | 0,4 |
| Imax AUmax VACR Ohm  | 1,10,60,44 |